

MA2J1160G

Silicon epitaxial planar type

For switching circuits

■ Features

- Allowing high-density mounting
- Soft recovery characteristic: $t_{rr} = 100$ ns

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V_{RM}	40	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Peak forward current	I_{FM}	225	mA
Non-repetitive peak forward surge current *	I_{FSM}	500	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $t = 1$ s

■ Package

- Code
SMini2-F3
- Pin Name
1: Anode
2: Cathode

■ Marking Symbol: 1H

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

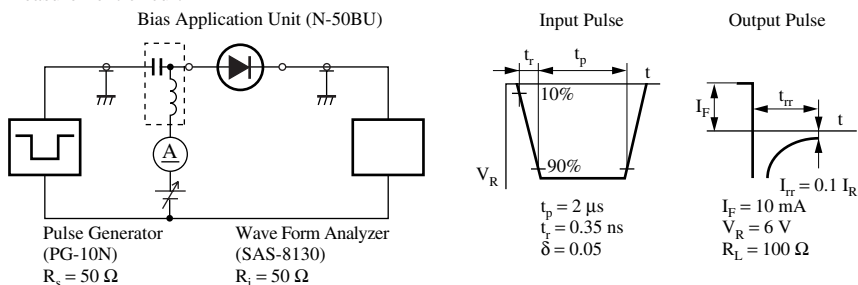
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100$ mA			1.2	V
Reverse voltage	V_R	$I_R = 100$ μA	35			V
Reverse current	I_{R1}	$V_R = 15$ V			5	nA
	I_{R2}	$V_R = 40$ V			10	
	I_{R3}	$V_R = 35$ V, $T_a = 100^\circ\text{C}$			100	μA
Terminal capacitance	C_t	$V_R = 6$ V, $f = 1$ MHz		1.0	2.0	pF
Forward dynamic resistance *1	r_f	$I_F = 3$ mA, $f = 30$ MHz			3.6	Ω
Reverse recovery time *2	t_{rr}	$I_F = 10$ mA, $V_R = 6$ V $I_{rr} = 0.1 I_R$, $R_L = 100$ Ω			100	ns

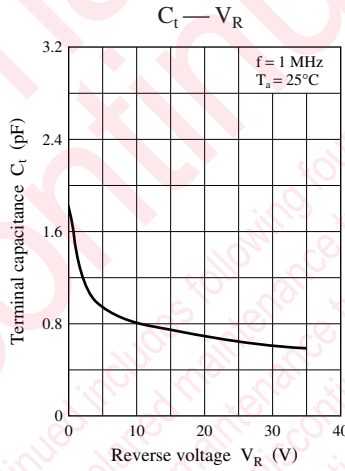
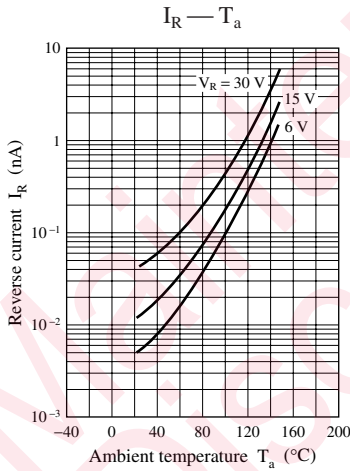
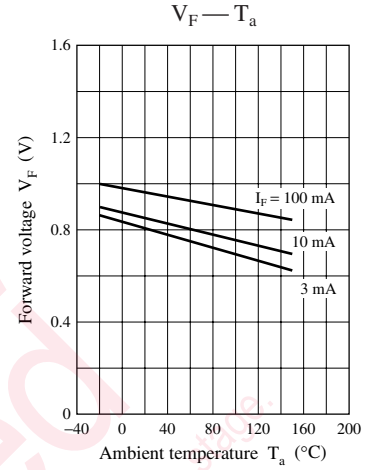
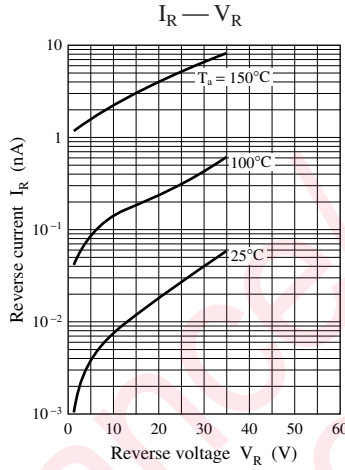
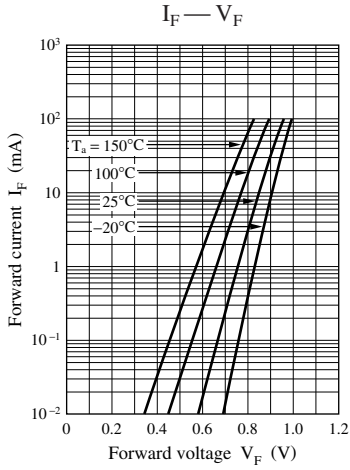
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 10 MHz.

3. *1: YHP 4191A RF IMPEDANCE ANALYZER

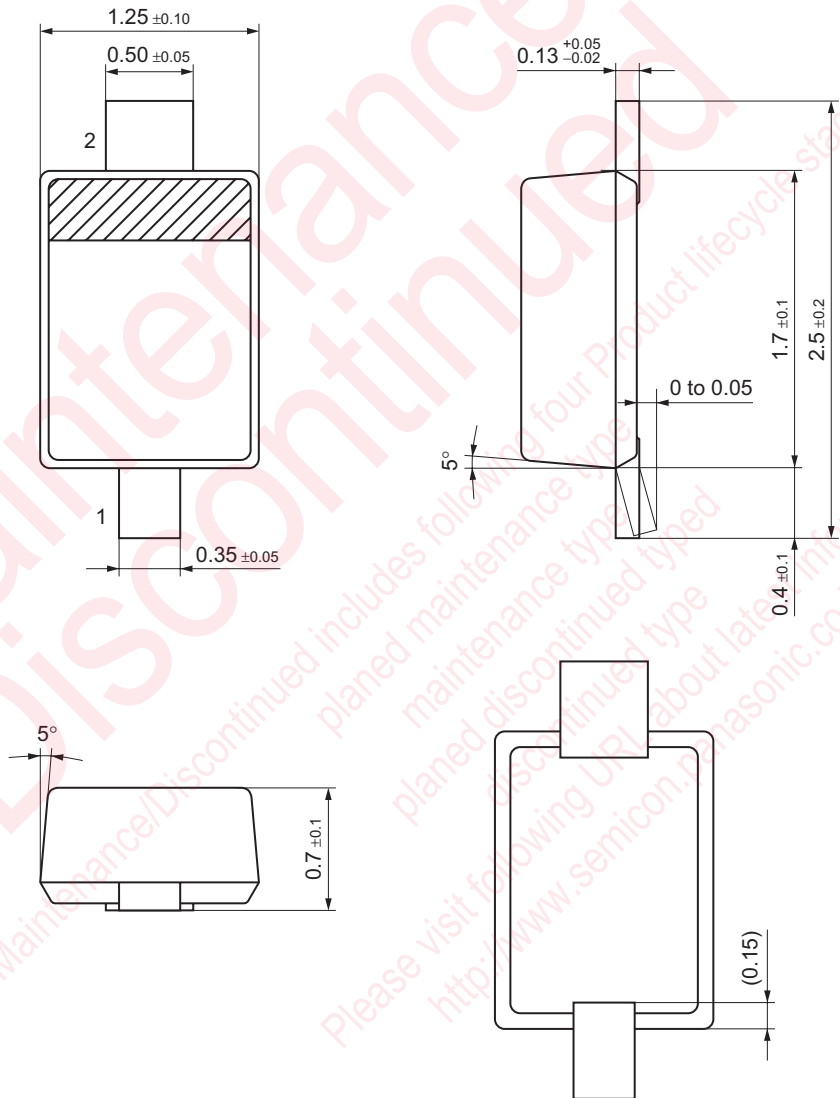
*2: t_{rr} measurement circuit





SMini2-F3

Unit: mm



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